

DesignCon 2009: Molex Incorporated to Showcase High Performance Interconnect Technologies

LISLE, Ill. – January 20, 2009 –Molex Incorporated announced today that it will conduct several demonstrations featuring its newest and highest performing interconnect solutions at DesignCon 2009, February 2-5.

Press members and show attendees are invited to visit Molex (booth 511) to see and discuss the latest in interconnect design solutions, including:

- **ZXP™ modular I/O interconnect system** - Molex will demonstrate the electrical performance of its next generation of small form pluggable interfaces, ZXP. This connector will support data transmission at speeds beyond SFP+, up to and beyond 17 Gbps. ZXP technology is intended to support development of the next generation of applications, particularly 16 Gbps Fibre Channel. The technology will also lend itself to very high speed four lane interconnects to support emerging protocols such as 100 Gbps Ethernet.
- **14" SEARAY* copper flex cable assembly using Solder Charge Technology** - Molex will showcase its Solder Charge technology by facilitating silicon-driven 10 Gbps data rate signal transmission through a 14" SEARAY copper flex cable assembly. Solder Charge technology is a new SMT attach method for printed circuit board adhesion. In the connector assembly process, stamping a Solder Charge is less expensive and more precise than melting a solder ball onto a metal lead.

The SEARAY Slim, a four-row, high-speed connector offers flexibility and headroom for next-generation protocol improvements. It leverages Molex's Solder Charge technology and squeezes 12.5 Gbps speeds in envelopes commonly limited to two-row architectures. Available in 7 to 15mm stack heights and 40 to 200 circuits, its narrow profile facilitates unobstructed airflow in a system.

- **The Impact™ backplane connector system** – Molex will showcase a 20 Gbps data rate signal transmission over a 1.0m copper backplane channel using the Impact evaluation backplane, along with an Avago Technologies' 65Nm embedded SerDes. The Impact backplane connector system is the fastest, densest backplane connector on the market. Functioning at data rates over 20 Gbps and offering superior signal density up to 80 differential pairs per inch, Molex's Impact system provides significant channel performance headroom for future system upgrades in both traditional backplane and midplane architectures. Impact is a finalist for the 2009 DesignVision Awards.
- **The GbX I-Trac™ backplane connector system** – Molex will demonstrate a 10.3 Gbps (IEEE 802.3ap 10GBASE KR) data signal through Molex's orthogonal copper GbX I-Trac backplane. GbX I-Trac is a broadside coupled, skew-equalized, 12.5 Gbps solution with low cross talk and superior impedance control. A unique feature of the GbX I-Trac system is the capability to use the same standard connector blocks for both traditional and orthogonal architectures. Market-leading 10 Gbps and IEEE 802.3ap 10GBASE KR platform designs currently use the 7-, 11- and 15-row GbX I-Trac technology.

About Molex

Molex Incorporated is a 70-year-old global manufacturer of electronic, electrical and fiber optic interconnection systems. Based in Lisle, Illinois, USA, the company operates 45 manufacturing locations in 17 countries. The Molex website is www.molex.com.

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